

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: Young-Hee SONG, et al.

Serial No.: 10/651,813 Examiner: Williams, Alexander O.

Filed: August 28, 2003 Group Art Unit: 2826

Confirmation No.: 9556

For: SEMICONDUCTOR CHIP HAVING BOND PADS AND MULTI-CHIP  
PACKAGE

Date: June 27, 2006

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT**

Responsive to the Office Action, Paper No. 20060316, dated March 27, 2006, please  
amend the application as follows.

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3  
of this paper.

**Remarks/Arguments** begin on page 8 of this paper.